

Levio Sorting

Contactless fully automatic die sorting

Levio Sorting is a fully automatic contactless sorting machine. Touchless Automation contactless handling technology allows to manipulate components of any material with a delicacy never reached before.

Levio Sorting can handle a wide range of standard inputs and outputs media, which allows it to be integrated into any production flow. The trackability of each component enables to have complete control of the process quality.

An optional ISO 14644-1 Class 6 enclosure and Ionizers for ESD protection complete the machine and reach for even higher process quality.

Component features

- Minimum size: 0.5 mm
- Maximum size: 10 mm
- Minimum thickness: 100 µm
- Contactless handling of any material (GaAs, GaN, Glass, Si, ...)

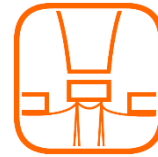
Flexible sorting

- Visual inspection of top side
- Electronic map sorting
- Multiple output trays

AUTOMATIC
INSPECTION



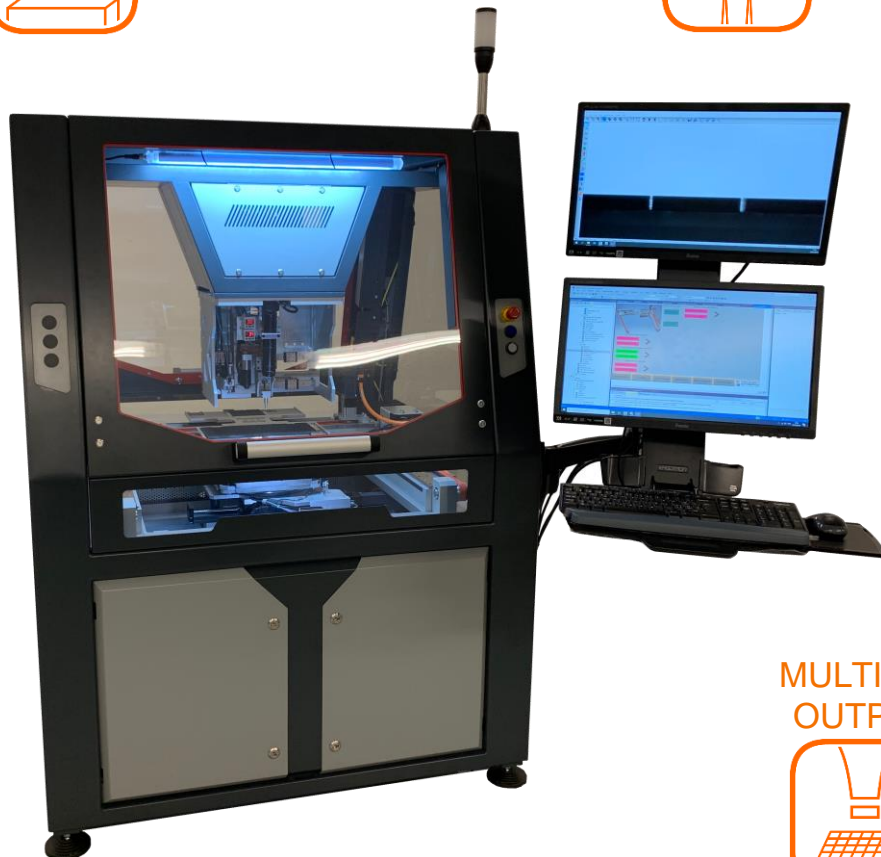
CONTACTLESS
DIE EJECTION



CLEANROOM
ENCLOSURE
ISO 14644-1
Class 6



CONTACTLESS
HANDLING

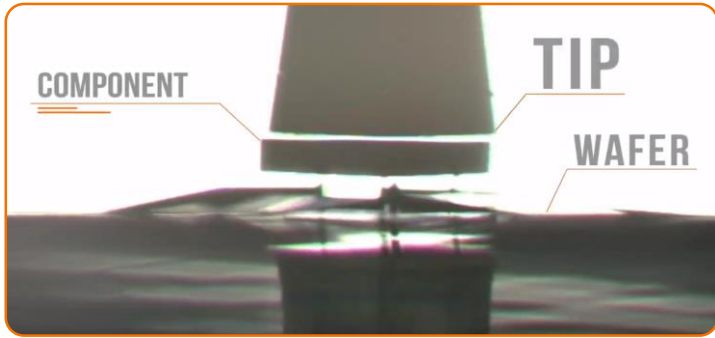


ELECTRONIC
MAP SORTING



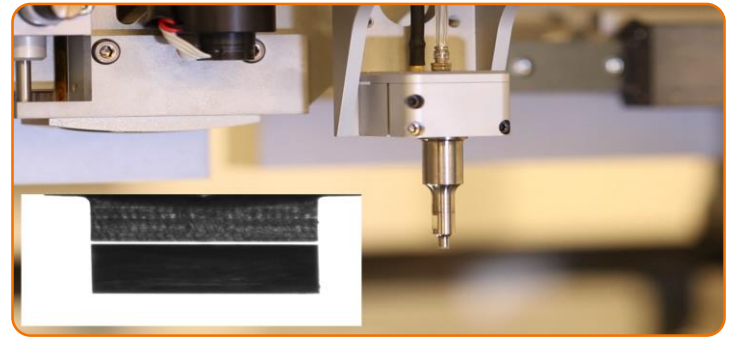
MULTIPLE
OUTPUT





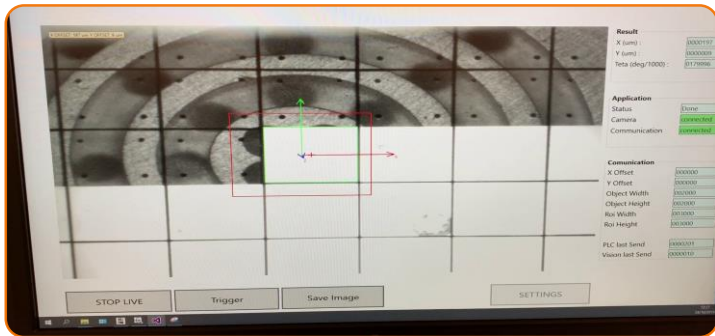
Contactless die ejection

Components can be picked up from a wide range of adhesive tapes, all while never touching the top side. An adaptive vision system, with optional OCR, allows for automatic component detection.



Contactless manipulation

Touchless Automation technology manipulates components without any physical contact. This thanks to a combination of vacuum and air streams that allows for any material to be handled.



Automatic top side inspection

The visual inspection system detects defects or marks on top side of the component. The component are then sorted accordingly into different output trays.



Electronic map sorting

Alternatively to component inspection, the system can sort components into different trays based on an electronic input map.



Multiple output carriers

Automatic sorting of the components into multiple output trays, allowing very flexible processes. Placing precision of $\pm 10 \mu\text{m}$.

 **SWISS MADE**

Touchless Automation GmbH

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Machine Dimensions

- Width 1200mm
- Depth 1150mm
- Height 1700mm
- Weight: approx. 900 kg

Input

- 4", 6", 8", 12" input frame
- 6 waffle trays 4"
- 20 waffle trays 2"
- 2 Jedec trays

Die features

- Min size: 0.5 mm
- Max size: 10 mm
- Min thickness: 100 μm
- Any material

Throughput

- 800 UPH with die ejection
- 1200 UPH from tray
- Final throughput depends on inspection requirements

Requirements

- Voltage 220-240 VAC
- Current 12A max
- Air pressure 6 Bars max

Output

- 6 waffle/Gel Pak® trays 4"
- 20 waffle/Gel Pak® trays 2"
- 2 Jedec trays

Placing Precision

- $\pm 10 \mu\text{m}$
- ± 1 degree theta